



081209 Datasheet

DiGi Electronics Part Number	0534081209-DG
Manufacturer	Molex
Manufacturer Product Number	0534081209
Description	CONN PLUG 120POS SMD GOLD

<https://www.DiGi-Electronics.com>

Detailed Description 120 Position Connector Plug, Center Strip Contacts
Surface Mount Gold

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Purchase and inquiry

Manufacturer Product Number:

0534081209

Series:

53408

Connector Type:

Plug, Center Strip Contacts

Pitch:

0.039" (1.00mm)

Mounting Type:

Surface Mount

Contact Finish:

Gold

Mated Stacking Heights:

18mm

Base Product Number:

053408

Manufacturer:

Molex

Product Status:

Obsolete

Number of Positions:

120

Number of Rows:

2

Features:

Board Guide, Solder Retention

Contact Finish Thickness:

10.0µin (0.25µm)

Height Above Board:

0.644" (16.35mm)

Moisture Sensitivity Level (MSL):

1 (Unlimited)

ECCN:

EAR99

Environmental & Export classification

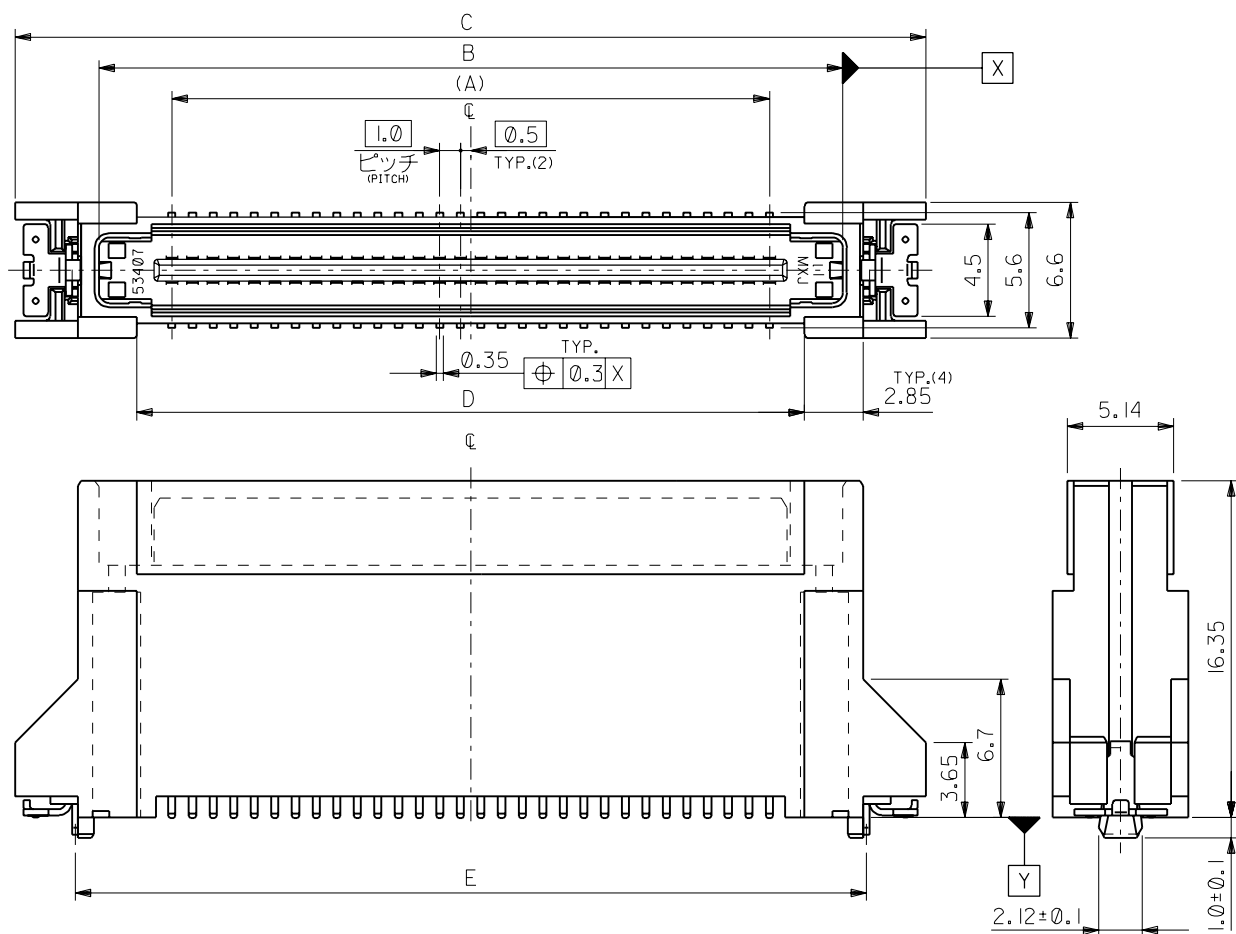
RoHS Status:

RoHS non-compliant

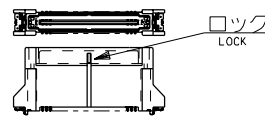
REACH Status:

REACH Unaffected

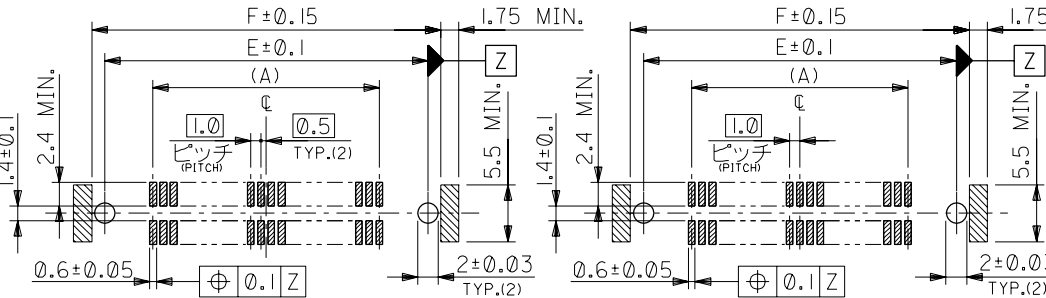
DWG. NO. SD-53408-***0



- 注) 1. 材質 MATERIAL
 HOUSING: G.F.LCP, WHITE, UL94V-0
 ターミナル: 燐青銅 (t = 0.2)
 TERMINAL: PHOSPHOR BRONZE
 金属ペグ: 燐青銅
 METAL PEG: PHOSPHOR BRONZE
2. ヌッキ仕様 PLATING
 ターミナル 接点部: 金メッキ 0.25 μmMIN.
 TERMINAL CONTACT AREA: GOLD 0.25 μmMIN.
 半田付け部: 半田メッキ 1.0 μmMIN.
 SOLDER TAIL AREA: TIN-LEAD 1.0 μmMIN.
 下地メッキ: ニッケルメッキ 2.0 μmMIN.
 UNDER-PLATING: NICKEL 2.0 μmMIN.
 金属ペグ 半田付け部: 半田メッキ 3.5 μmMIN.
 METAL PEG SOLDER TAIL AREA: TIN-LEAD 3.5 μmMIN.
3. 推奨基板厚 RECOMMENDED PCB THICKNESS
 1.0 ± 0.1mm MIN.
4. テールのバラツキ寸法 TAIL COPLANARITY
 テールは、Y面を基準とし、上へ 0.02 下へ 0.15 の範囲にのみ、且つテール平坦度は 0.15 とする。
 TAILS TO BE WITHIN 0.02 UPWARD AND 0.15 DOWNWARD FROM Y-DATUM PLANE, AND TAIL COPLANARITY TO BE 0.15.
5. ロックは、20、24、50極に設置する。
 LOCK TO BE ADDED TO 20, 24 AND 50 CKTS.
6. 梱包 PACKAGING
 本製品はスティック梱包とし梱包後のENG. NO. は 53408-***9とする。
 THIS PRODUCTS TO BE PACKED IN TUBE. ENG. NO.: 53408-***9
7. 同一基板内に複数個 (2ヶ以上) の使用は避けてください。
 MXJ DOES NOT RECOMMEND THE USAGE OF TWO OR MORE OF THESE CONNECTORS BETWEEN A SINGLE PAIR OF P.C.BOARD.



80.9	78.4	72.4	84.2	76.02	69	53408-1400	140
70.9	68.4	62.4	74.2	66.02	59	53408-1200	120
60.9	58.4	52.4	64.2	56.02	49	53408-1000	100
50.9	48.4	42.4	54.2	46.02	39	53408-0800	80
40.9	38.4	32.4	44.2	36.02	29	53408-0600	60
35.9	33.4	27.4	39.2	31.02	24	53408-0500	50
22.9	20.4	14.4	26.2	18.02	11	53408-0240	24
20.9	18.4	12.4	24.2	16.02	9	53408-0200	20
F	E	D	C	B	(A)	ENG. NO.	種数 NO. OF CKTS.



推奨基板寸法 (20, 24, 60, 80, 100, 120, 140極)
 RECOMMENDED PCB PATTERN LAYOUT (20, 24, 60, 80, 100, 120, 140 CKTS.)
 (SCALE 2-1)

推奨基板寸法 (50極)
 RECOMMENDED PCB PATTERN LAYOUT (50 CKTS.)
 (SCALE 2-1)

角度 ANGLE	±3°
30以上 OVER	+0.3
10以上 30未滿 UNDER	+0.25
未滿 UNDER	+0.2

G	変更 REVISION	(JD2001-1424)	T.H.	T.H.	10/24/19
F	変更 REVISION	(JD60150)	J.M.	Y.I.	19/08/10
E	変更 REVISION	(T40044)	S.A.	J.M.	19/01/27
D	変更 REVISION	(T30585)	S.M.	M.S.	19/12/1
C	変更 REVISION	(T30434)	S.M.	S.I.	19/9/8
B	変更 REVISION	(T30355)	J.M.	Y.I.	19/7/15
A	変更 REVISION	(T30275)	S.M.	M.S.	19/6/8
0	新規作成 RELEASED		H.H.	M.S.	19/2/18
記号 LTR	変更内容 REVISION RECORD		DR. CHK.	日付 DATE	

材料 MATERIAL 注参照 SEE NOTES

仕上げ FINISH 注参照 SEE NOTES

適用電線範囲 WIRE RANGE —

被覆外径 INS. RANGE —

DRAWN BY H. Hirata

CHK'D BY M. Yaguchi

APP'D BY [Signature]

尺度 SCALE 4-1

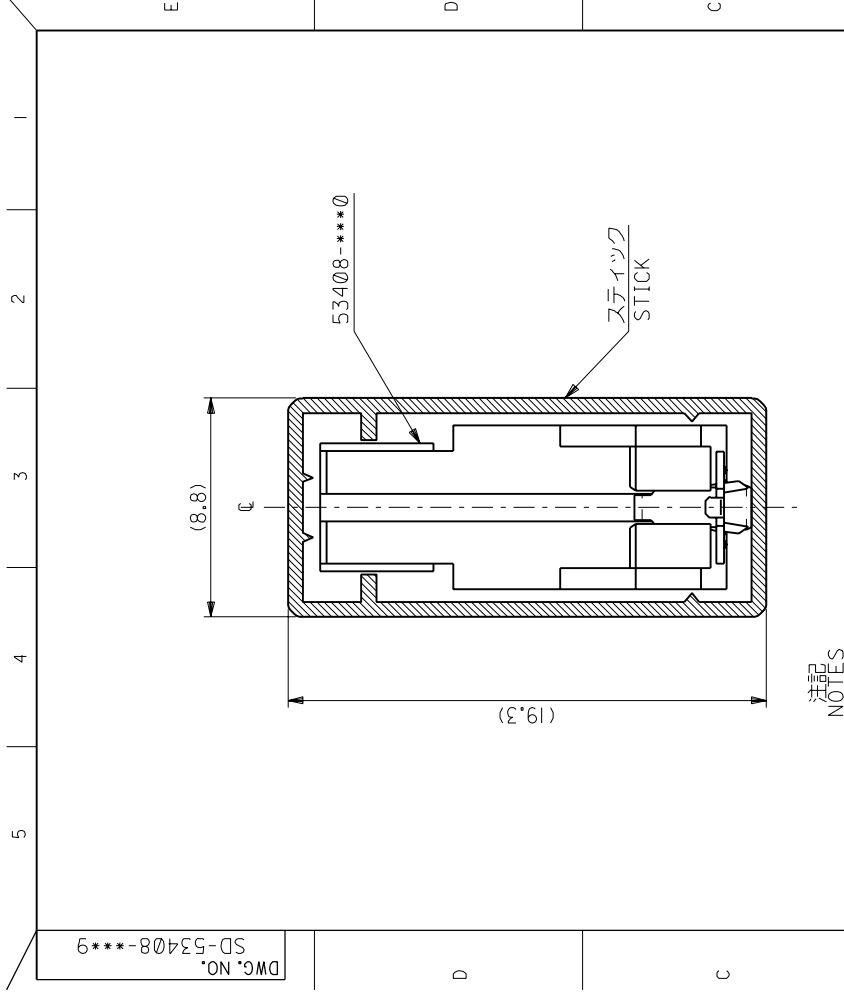
molex MOLEX-JAPAN CO., LTD.
 日本モレックス株式会社

REVISE ONLY ON CAD SYSTEM

TITLE 名称
 1.0 B-T-O-B
 S/T PLUG HS'G ASS'Y

DWG. NO. SD-53408-***0

REV G



DWG. NO. SD-53408-***9

DIMENSIONS IN METRIC DO NOT SCALE DRAWING

6	53408-1409	140
7	53408-1209	120
8	53408-1009	100
10	53408-0809	80
13	53408-0609	60
14	53408-0509	50
21	53408-0249	24
23	53408-0209	20

注記
NOTES

1. スティック両端はキャップ止め。
BOTH ENDS WITH CAPS.
2. 全長: 600±2
TOTAL LENGTH
3. 肉厚: 0.6±0.2
THICKNESS

角度	ANGLE	±3°
30以上 OVER		+0.3
10以上 UNDER		+0.25
10以下 UNDER		+0.2

一般公差
GENERAL TOLERANCES

G	変更	(JIS B 0200-1-1624)	K,T,H	01/04/79
F	変更	(JIS B 0150)	M,N	05/08/78
E	変更	(JIS B 0648)	V,X,J	03/12/74
D	変更	(JIS B 0585)	S,J,M	03/12/71
C	変更	(JIS B 0585)	S,M,S	03/11/75
B	変更	(JIS B 0434)	S,S,I	03/12/78
A	変更	(JIS B 0275)	S,M,S	03/12/78
0	新規作成 RELEASED	(JIS B 010)	S,M,S	03/12/79

材料	MATERIAL	ポリ塩化ビニル
スティック	STICK	P.V.C.
仕上げ	FINISH	—
適用電線範囲	WIRE RANGE	—
液層外径	INS. RANGE	—

DRAWN BY	CHK'D BY	REV
J. Inoue	H. Inoue	G
APP'D BY	SCALE	5-1
日付	DATE	

MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社
REVISE ONLY ON CAD SYSTEM
TITLE 名称
53408-***0 STICK PACKAGING
DWG. NO. SD-53408-***9
REV G

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